



13 same 18

L1: (8332) edge adj effect
 L2: (911) terminal adj effect
 L3: (9221) 11 or 12
 L4: (16560) (205/50-333) :CCLS.
 L5: (61889) wafer or semiconductor
 L6: (97) 13 and 14 and 15
 L7: (97) 13 and 14 and 15
 L8: (13416) seed adj layer
 L9: (66) 17 and 18

L10: (46) 13 same 18

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Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Inventor	U	S	C	P	1	3	pre
1 US 200601024677/20060518 A1	21	Current collimation for thin seed and direct plating	204/230.2		Herchen, Harald et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>						
2 US 20050284755/20051229 A1	12	Substrate support element for an electrochemical plating cell	204/297.01		Wang, You et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>						
3 US 20050274619/20051215 A1	9	Modified electroplating solution components in a low-acid electrolyte	205/761	205/261; 205/84	Zierath, Daniel J. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>						
4 US 20050199502/20050915 A1	14	Method for electroplating on resistive substrates	205/102	205/291	Andricacos, Panayotis et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>						
5 US 20050178667/20050818 A1	35	Method and systems for controlling current in electrochemical processing of apparatus having plating solution containers with current applying anodes	205/123	205/157; 205/171	Wilson, Gregory J. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>						
6 US 20050173241/20050811 A1	16	Apparatus having plating solution containers with current applying anodes	204/228.9	205/63; 205/96	Chalupka, Radek P. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>						
7 US 20050153548/20050714 A1	6	Method for fabricating semiconductor device to minimize terminal effect in	438/687	257/B21.174; 257/B21.584	Hong, Ji Ho et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>						
8 US 20050153547/20050714 A1	4	Methods of forming copper interconnections using electrochemical	438/650	438/653; 438/677;	Hong, Ji Ho et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>						
9 US 20050092602/20050505 A1	13	Electrochemical plating cell having a membrane stack	204/295		Herchen, Harald et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>						
10 US 20050092601/20050505 A1	12	Electrochemical plating cell having a diffusion member	204/252	204/263	Herchen, Harald et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>						
11 US 20050077181/20050414 A1	9	Modified electroplating solution components in a low-acid electrolyte	205/81		Zierath, Daniel J. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>						
12 US 20050016681/20050127 A1	15	Method and apparatus for the electrochemical deposition and	156/345.12	257/B21.175	Emesh, Ismail et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>						